

# **Product Description**

The PE42641 is a HaRP<sup>TM</sup>-enhanced SP4T RF Switch developed on the UltraCMOS<sup>®</sup> process technology. This switch contains 4 identical WEDGE/ CDMA compliant TX paths and can be used in various GSM and WCDMA mobile applications as well as other wireless applications up to 3000 MHz. It is also suitable for antenna band switching and switchable matching networks for cellular and non-cellular mobile applications. It integrates on-board CMOS control logic with a low voltage CMOS-compatible control interface and requires no DC blocking capacitors. This RoHScompliant part is available in a standard 3 x 3 x 0.75mm QFN package.

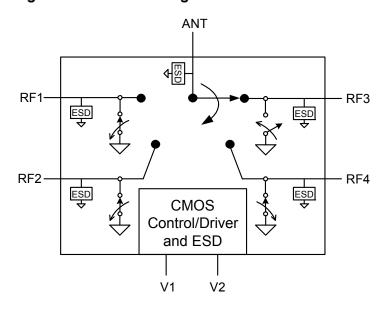
Peregrine's HaRP<sup>™</sup> technology enhancements deliver high linearity and exceptional harmonics performance. It is an innovative feature of the UltraCMOS<sup>®</sup> process, providing performance superior to GaAs with the economy and integration of conventional CMOS.

# Product Specification PE42641

SP4T UltraCMOS<sup>®</sup> RF Switch 100 MHz – 3.0 GHz

## Features

- Symmetric, High-Power SP4T: All ports WEDGE/CDMA-Compliant
- Very Low Insertion Loss: 0.45 dB @ 1000 MHz, 0.6 dB @ 2000 MHz
- HaRP<sup>™</sup> enhanced Technology for Unparalleled Linearity
  - Low harmonics of  $2f_{o} = -86$  dBc and  $3f_{o} = -81$  dBc at +35 dBm
  - IMD3 of -110 dBm at WCDMA Band I
  - IIP3 of +68 dBm
- Very high isolation: 35 dB @ 900 MHz, 29 dB @ 1900 MHz
- Exceptionally high ESD tolerance:
  - Class 3 (4.0 kV HBM) on ANT pin
  - Class 2 (2.0 kV HBM) on all pins
- Integrated decoder for 2-pin control
  - Accepts 1.8V and 2.75V levels
- Low 4.5 ohm series ON resistance
- No blocking capacitors required



# Figure 1. Functional Diagram

## Figure 2. Package Type

16-lead 3x3 mm QFN





# Table 1. Electrical Specifications Temp = 25°C, $V_{DD}$ = 2.75V ( $Z_S = Z_L = 50 \Omega$ )

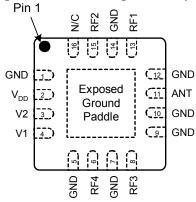
Parameter	Condition	Min	Тур	Max	Units
Operational Frequency		100		3000	MHz
	ANT - RF (850 / 900 MHz)	-	0.45	0.65	dB
Insertion Loss <sup>1</sup> (Symmetric Ports)	ANT - RF (1800 / 1900 MHz)	-	0.5	0.7	dB
	ANT - RF (1900 / 2200 MHz)	-	0.55	0.75	dB
	850 / 900 MHz	-	25	-	dB
Return Loss (Active Ports)	1800 / 1900 MHz	-	19	-	dB
	1900 / 2100 MHz	-	18	-	dB
Isolation	RF - ANT (850 / 900 MHz)	31	35	-	dB
	RF - ANT (1800 / 1900 MHz)	25	29	-	dB
	RF - ANT (1900 / 2200 MHz)	23.5	27.5	-	dB
	35 dBm output power, 850 / 900 MHz		-86	-80	dBc
2nd Harmonic	33 dBm output power, 1800 / 1900 MHz		-87	-78	dBc
3rd Harmonic	35 dBm output power, 850 / 900 MHz		-81	-73.5	dBc
	33 dBm output power, 1800 / 1900 MHz		-80	-72.5	dBc
IMD3 distortion at 2.14 GHz	RF Measured at 2.14 GHz at Ant port, input +20 dBm CW signal at 1.95 GHz and -15 dBm CW signal at 1.76 GHz		-110		dBm
Switching time	(10-90%) (90-10%) RF		2	5	μs

Note: 1. The typical ON Resistance value at DC is 4.5  $\ensuremath{\Omega}$ 

Parameter	Condition	Min	Тур	Max	Units
	ANT - RF (850 / 900 MHz)	-	0.5	0.7	dB
Insertion loss (2.65V, 85C)	ANT - RF (1800 / 1900 MHz)	-	0.55	0.75	dB
	ANT - RF (1900 / 2200 MHz)	-	0.6	0.8	dB
	850 / 900 MHz	-	25	-	dB
Return Loss (Active Ports) (2.65V, 85C)	1800 / 1900 MHz	-	19	-	dB
(2.001, 000)	1900 / 2100 MHz	-	18	-	dB
Isolation (2.65V, 85C)	RF - ANT (850 / 900 MHz)	30.5	34.5	-	dB
	RF - ANT (1800 / 1900 MHz)	24.5	28.5	-	dB
	RF - ANT (1900 / 2200 MHz)	23	27	-	dB
	35 dBm output power, 850 / 900 MHz		-84	-78	dBc
2nd Harmonic (2.65V, 85C)	33 dBm output power, 1800 / 1900 MHz		-85	-76	dBc
3rd Harmonic (2.65V, 85C)	35 dBm output power, 850 / 900 MHz		-79	-71.5	dBc
	33 dBm output power, 1800 / 1900 MHz		-78	-70.5	dBc
IMD3 distortion at 2.14 GHz (2.65V, 85C)	RF Measured at 2.14 GHz at Ant port, input +20 dBm CW signal at 1.95 GHz and -15 dBm CW signal at 1.76 GHz		-108		dBm
Switching time	(10-90%) (90-10%) RF		2	5	μs



## Figure 3. Pin Configuration (Top View)



## **Table 3. Pin Descriptions**

Pin Name	Description
GND	Ground
V <sub>DD</sub>	Supply
V2	Switch control input, CMOS logic level
V1	Switch control input, CMOS logic level
GND	Ground
RF4 <sup>2</sup>	RF Port 4
GND	Ground
RF3 <sup>2</sup>	RF Port 3
GND	Ground
GND	Ground
ANT <sup>2</sup>	RF Common – Antenna
GND	Ground
RF1 <sup>2</sup>	RF Port 1
GND	Ground
RF2 <sup>2</sup>	RF Port 2
N/C	No Connect
GND	Ground for proper device operation
	GND   V <sub>DD</sub> V2   V1   GND   RF4 <sup>2</sup> GND   RF3 <sup>2</sup> GND   GND   GND   RF1 <sup>2</sup> GND   RF1 <sup>2</sup> GND   RF2 <sup>2</sup> N/C

Blocking capacitors needed only when non-zero DC voltage present Note:

## Table 4. Operating Ranges

Parameter	Symbol	Min	Тур	Max	Units
Temperature range	T <sub>OP</sub>	-40		+85	°C
V <sub>DD</sub> Supply Voltage	V <sub>DD</sub>	2.65	2.75	2.85	V
$I_{DD}$ Power Supply Current (V <sub>DD</sub> = 2.75V)	I <sub>DD</sub>		13	50	μA
RF input power <sup>3</sup> (VSWR $\leq$ 3:1) 824-915 MHz	P <sub>IN</sub>			+35	dBm
RF input power <sup>3</sup> (VSWR $\leq$ 3:1) 1710-1910 MHz	ΓIN			+33	ubiii
Control Voltage High	V <sub>IH</sub>	1.4			V
Control Voltage Low	V <sub>IL</sub>			0.4	۷

Note: 3. Assumes RF input period of 4620 µs and duty cycle of 50%

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Symbol	Parameter/Conditions		Max	Units	
V <sub>DD</sub>	Power supply voltage	-0.3	4.0	V	
Vi	Voltage on any DC input	-0.3	V <sub>DD</sub> + 0.3	V	
T <sub>ST</sub>	Storage temperature range	-65	+150	°C	
B(50 O)	RF input power (50 Ω) <sup>4,5</sup> 824-915 MHz		+38	dBm	
P <sub>IN</sub> (50 Ω)	RF input power (50 Ω) <sup>4,5</sup> 1710-1910 MHz		+36		
P <sub>IN</sub> (∞:1)	RF input power (VSWR = (∞:1) <sup>4,5</sup> 824-915 MHz		+35	– dBm	
	RF input power (VSWR = (∞:1) <sup>4,5</sup> 1710-1910 MHz		+33		
V <sub>ESD</sub> <sup>6</sup>	ESD Voltage, ANT pin		4000	V	
V ESD	ESD Voltage, all pins		2000	V	

#### **Table 5. Absolute Maximum Ratings**

Notes: 4. Assumes RF input period of 4620 µs and duty cycle of 50% V<sub>DD</sub> within operating range specified in *Table 4* ESD Voltage (HBM, MIL-STD-883 Method 3015.7)

Exceeding absolute maximum ratings may cause permanent damage. Operation should be restricted to the limits in the Operating Ranges table. Operation between operating range maximum and absolute maximum for extended periods may reduce reliability.

## Table 6. Truth Table

Path	V2	V1
ANT – RF1	0	0
ANT – RF2	1	0
ANT – RF3	0	1
ANT – RF4	1	1

## **Electrostatic Discharge (ESD) Precautions**

When handling this UltraCMOS® device, observe the same precautions that you would use with other ESDsensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the specified rating.

#### Latch-Up Avoidance

Unlike conventional CMOS devices, UltraCMOS® devices are immune to latch-up.

#### Moisture Sensitivity Level

The Moisture Sensitivity Level rating for the PE42641 in the 16-lead 3x3 QFN package is MSL1.



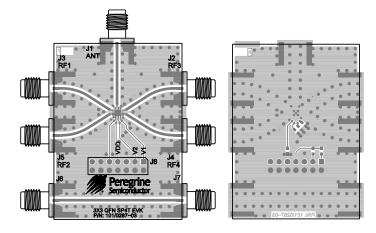
# **Evaluation Kit**

The SP4T switch EK Board was designed to ease customer evaluation of Peregrine's PE42641. The RF common port is connected through a 50  $\Omega$  transmission line via the top SMA connector, J1. RF1, RF2, RF3 and RF4 are connected through 50  $\Omega$  transmission lines via SMA connectors J3, J5, J2 and J4, respectively. A through 50  $\Omega$  transmission is available via SMA connectors J6 and J7. This transmission line can be used to estimate the loss of the PCB over the environmental conditions being evaluated.

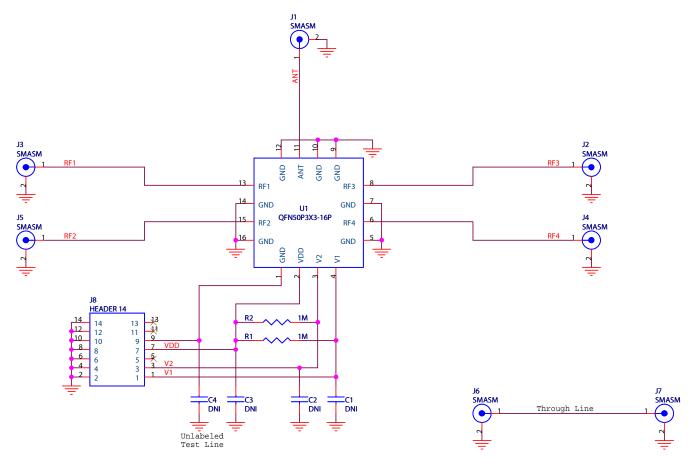
The board is constructed of a four metal layer FR4 material with a total thickness of 62 mils. The middle layers provide ground for the transmission lines. The transmission lines were designed using a coplanar waveguide with ground plane model using a trace width of 32 mils, trace gaps of 25 mils, and metal thickness of 2.1 mils.

### **Figure 4. Evaluation Board Layouts**

Peregrine Specification 101/0287





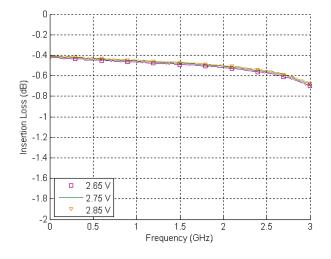


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# Figure 7. Insertion Loss: ANT-RF @ 2.75V

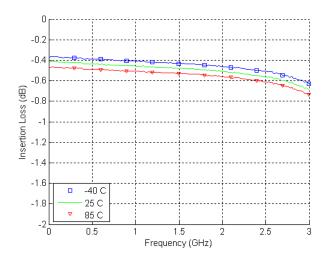


Figure 8. Isolation: ANT-RF @ 25°C

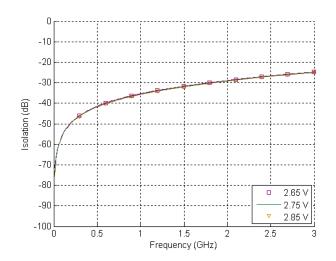
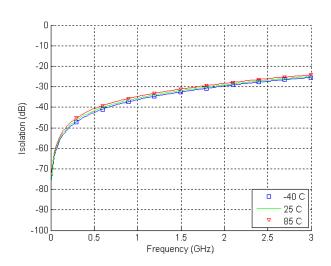
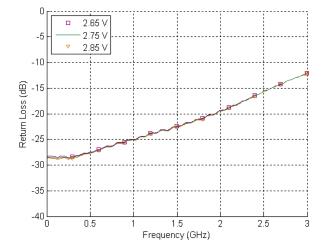


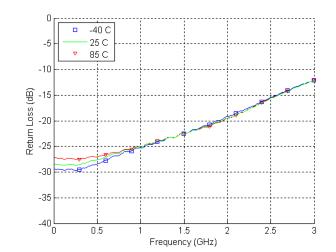
Figure 9. Isolation: ANT-RF @ 2.75V







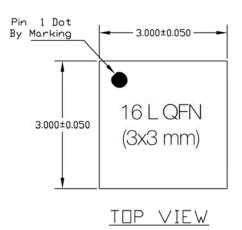
# Figure 10. Return Loss at active port @ 25°C

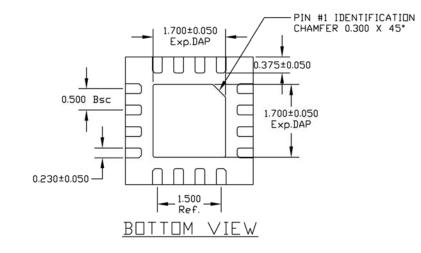


# Figure 11. Return Loss at active port @ 2.75V

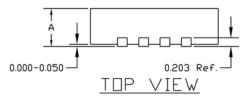


## Figure 12. Package Drawing





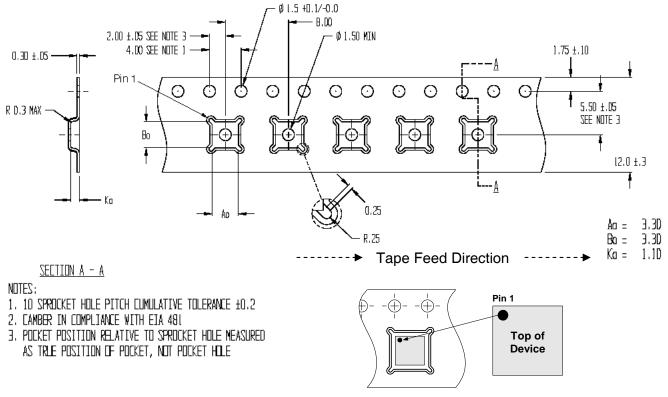
		QFN 3x3 mm
A	MAX	0.800
	NOM	0.750
	MIN	0.700





## Figure 13. Tape and Reel Specifications

16-lead 3x3 mm QFN



Device Orientation in Tape

#### **Table 7. Ordering Information**

Order Code	Part Marking	Description	Package	Shipping Method
EK42641-02 <sup>1</sup>	PE42641-EK	PE42641-16QFN 3x3mm-EK	Evaluation Kit	1 / Box
EK42641-03 <sup>1</sup>	PE42641-EK	PE42641-16QFN 3x3mm-EK	Evaluation Kit	1 / Box
PE42641MLIBB-Z <sup>1</sup>	42641	PE42641G-16QFN 3x3mm-3000C	Green 16-lead 3x3mm QFN	3000 units / T&R
PE42641MLBC-Z <sup>2</sup>	42641	PE42641G-16QFN 3x3mm-3000C	Green 16-lead 3x3mm QFN	3000 units / T&R

Notes: 1. Hana – AYT (Thailand) assembly house. Please contact factory for assembly house details.

2. Unisem assembly house. Please contact factory for assembly house details.

#### **Sales Contact and Information**

For sales and contact information please visit www.psemi.com.

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